

THE BEST SOLUTION PROVIDER



LBSemicon

L O O K B E Y O N D
T H E B E S T S O L U T I O N P R O V I D E R



LBSemicon

YOUR BEST OSAT PARTNER, VENTURING
INTO THE NEW WORLD WITH CUSTOMERS.
THE INNOVATIVE TECHNOLOGIES OF
LB SEMICON WILL BRING YOUR VISION TO LIFE.

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Made with eco-friendly paper and soy ink.
The mark of responsible forestry.

TOWARDS A BOND OF UNSHAKABLE TRUST

TRUST IS CRUCIAL FOR SUCCESS IN TODAY'S EVOLVING BUSINESS LANDSCAPE. LB SEMICON PRIORITIZES TRUST, AIMING TO BE A RELIABLE PARTNER TO CLIENTS.

1. LB Semicon

Company Philosophy

CEO's Greetings

Our Vision and Mission

Affiliated Companies

History

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COMPANY PHILOSOPHY

YOUR BEST OSAT PARTNER ADVENTURING TOWARDS A NEW WORLD WITH CUSTOMERS.

LB Semicon is a specialized OSAT company that provides a total solution for the post-production phase for semiconductors based on advanced technologies and a spirit of embracing challenges.

Our confidence in serving our customers with best solutions is demonstrated by the finest product we provide. Our drive to 'Look Beyond' is what motivates us to strive for the new world that our customers and we dream together.

Today, we endeavor to be the best partner to our customers as we work towards our shared vision.

If you have a dream for a new world, come and meet LB Semicon, the company that will work together with you to turn that dream into reality. We will always be your reliable partner until the day when your envisioned tomorrow is realized.

Let's start a new journey with us right now!

CEO'S GREETINGS

LB SEMICON'S INNOVATIVE TECHNOLOGIES CAN BRING YOUR VISION TO LIFE

LB Semicon is a total solution company in OSAT field that provides customers with full Turn Key service (Bumping, CP-test, Back-end, etc.) and FIWLP and FOWLP services for AI, Smartphones, Automobiles and Wearable devices.

Since the foundation of LB Semicon in 2000, we have continuously improved our technology through our experience and partnerships with leading domestic and overseas semiconductor manufacturers.

We are committed to upholding the reputation of Korea as a global semiconductor powerhouse, and we strive to consistently provide the highest quality products and services to ensure mutual growth and success with our valued customers.

Nick (Namseog) Kim



OUR VISION AND MISSION

**WITH OUR PARTNERS,
WE ENVISION A BRIGHTER FUTURE
THAT WE CALL 'HARMONY'.**



Meaning

"Look Beyond" is the identity of LB. The logo has 21 stars in shape of a person. At LB, we view every member as a 'STAR,' constantly striving for excellence. This ethos reflects our commitment to forging ahead towards a brighter future with our members.

Characteristics

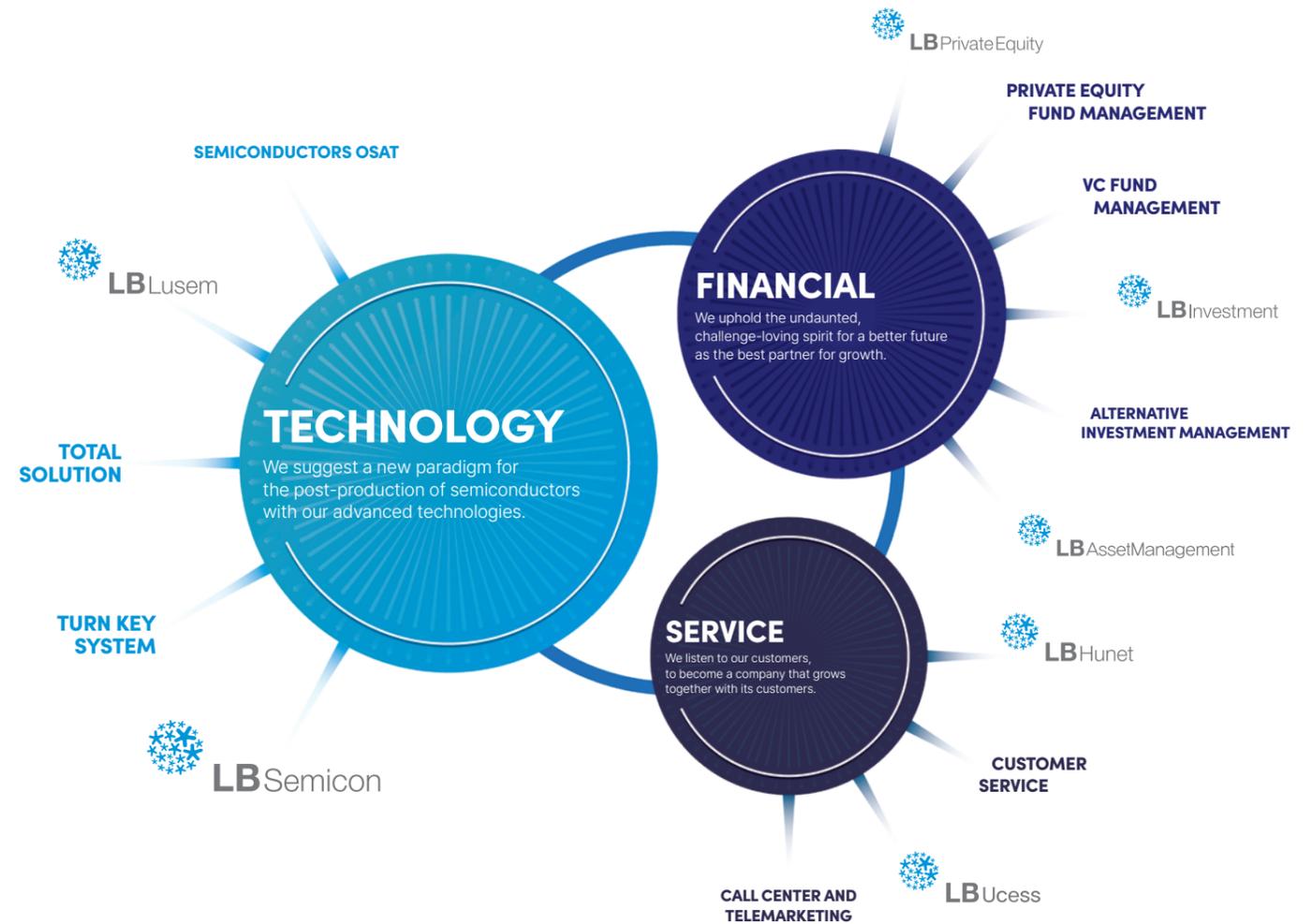
LB's symbol mark embodies the company's commitment to adaptability and agility in response to changing environments. The main theme color, "LB Blue," symbolizes honesty, youth, vast expanse of the sky and uncharted waters, and the limitless potential for innovation and progress, reflecting LB's continuous pursuit of new challenges and opportunities.

Look Beyond

Look Beyond embodies our commitment to progress steadily, continuously creating value for our customers and pushing beyond our limitations to reach new heights.

AFFILIATED COMPANIES

LB GROUP



Our Journey Towards a New Future.

LB Group has repeatedly pushed the limits of innovation and growth amidst numerous crises and challenges. Each member of LB has been drawing new standards, new directions, and more importantly, a new future for our partners in diverse industries.

HISTORY

LB SEMICON'S REMARKABLE JOURNEY THAT TURNED DREAMS INTO REALITY.



In the year 2000, Microscale, the predecessor of LB Semicon, started the OSAT business with only 1 billion won in capital, equipped with all the necessary production facilities for Flip Chip Wafer Bumping, making it the first of its kind in Korea. Although there were challenges as we ventured into uncharted territory, we used these difficulties as stepping stones for future growth. As a result, we were recognized as one of the top 500 Asia-Pacific companies by Deloitte, and have grown to become a reliable partner supporting the success of many global companies.

EMBARCKING ON A JOURNEY

- 2010**
 - 12 ISO/TS 16949:2009 certified.
 - 11 Named as one of the top 500 technology companies in Asia Pacific by Deloitte.
- 2009**
 - 12 Launched WLCSP products.
- 2008**
 - 01 Started Back-End Services.
- 2007**
 - 12 Mass production of the solder bump for CMOS image sensors.
- 2006**
 - 01 Rebranded company as LB Semicon.
- 2005**
 - 01 ISO 14001:1996 certified.
- 2003**
 - 11 5 Million Dollars Export Tower Award in celebration of the 40th Trade Day.
 - 06 Mass production of 8" Au Bump for Samsung Electronics.
 - 02 ISO 9001:2000 certified.
- 2001**
 - 09 Mass production for the 8" Wafer Test for Samsung Electronics.
- 2000**
 - 02 Founded as Microscale. (Capital 1 billion won)

LEAPING FORWARD TO THE FUTURE

- 2022**
 - 10 Expanded the Test Line in Anseong Plant, Korea.
 - 01 Mass production of SOC/CIS Wafer Test for Samsung Electronics.
- 2021**
 - 10 FOWLP development completed.
- 2019**
 - 12 ISO 45001:2018 certified.
- 2018**
 - 09 IATF 16949 certified.
 - 08 ISO 14001:2015 certified.
 - 03 Acquisition of LB Lusem.
- 2017**
 - 09 Received Certificate of Excellent Technology Evaluation Enterprise.
 - 03 Designated as Root-technology Specialized Company.
- 2015**
 - 04 Mass production of High Current WLCSP.
- 2014**
 - 05 Mass production of Thick Cu.
- 2013**
 - 06 CIS Wafer mass production test for SK Hynix.
- 2012**
 - 08 Mass production of 12" Au Bump and Solder Bump.
- 2011**
 - 04 Named as a 2011 KDB Global Star.
 - 01 Enlisted in KOSDAQ.

THE INNOVATIONS FOR TOMORROW

BOOST YOUR COMPETITIVENESS
WITH LB SEMICON'S
COMPREHENSIVE SOLUTIONS.



LBSemicon

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TOWARDS UNSTOPPABLE PROGRESS

FROM GOLD BUMPING, LB SEMICON HAS EXPANDED ITS BUSINESS TO SOLDER, CU PILLAR BUMPING, AND WLCSP. THROUGH THIS PROGRESS, LB SEMICON HAS MAINTAINED SOLID PARTNERSHIPS WITH TOP PARTNERS.

2. Business

Service Flow

FIWLP (Fan-In Wafer Level Package)

RDL (Redistribution Layer)

Bumping

CP-Test (Chip Probe Test)

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SERVICE FLOW

LB SEMICON PROVIDES CUSTOMIZED SERVICES WITH OUR TOTAL SOLUTIONS.

We are always prepared to provide solutions tailored to our customers' unique concerns. At LB Semicon, we constantly explore our customers' needs and strive to understand and address even their unspoken worries. Whatever challenges you may face, LB Semicon is here to listen and offer you a personalized solution that meets your needs. Let us help you find the solutions you need.



WAFER FAB OUT

OPTIMAL SOLUTION FOR EACH CUSTOMER

SHIPPING



BUMPING

WLP

- FIWLP
- FOWLP

RDL

- Direct RDL
- Au RDL

AU BUMPING

- Gold Bump

SOLDER BUMPING

- Solder Bump
- Cu Pillar Bump
- Cu-Ni-Au Bump



CP-TEST

CP-TEST

- DDI
- PMIC
- CIS
- SoC
- RE-CON



BACK END

BACK-END

- Laminating
- Back Grinding
- Back Side Coating
- Laser Marking
- Foil Mount
- Laser Grooving
- Dicing Sawing



ASSEMBLY

COF ASSEMBLY LB LUSEM

- Plasma
- Post AVI
- UV Irradiation
- Pick & Place
- Tape & Reel
- AVI Visual Inspection
- Packing



FINAL TEST

COF FINAL TEST LB LUSEM

- Final Test

FIWLP | Fan-In Wafer Level Package



FIWLP is an advanced version of conventional packaging where wafers are separated into chips and packaged afterwards. In FIWLP, packaging is performed at the wafer level to produce finished products.

Application :
PMIC / RF & BB SoC / Transceiver / AOC / Sensors



FIWLP Line-up

Conventional WLP Magnetic Embedded

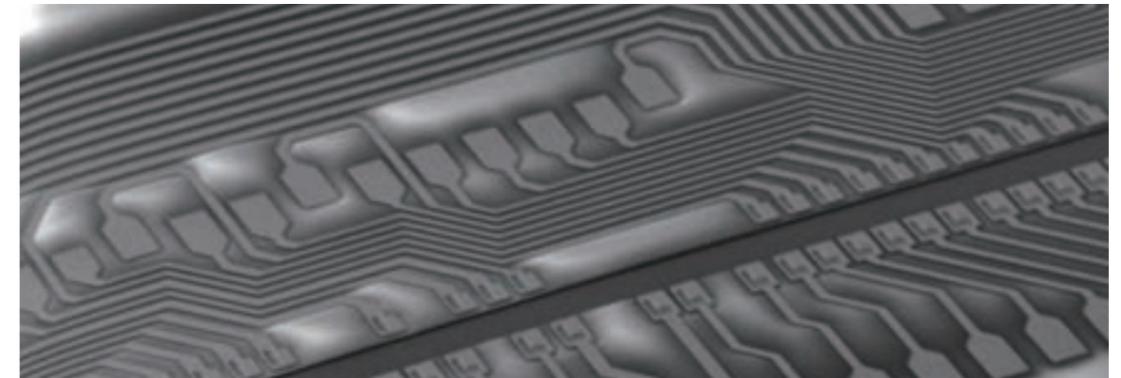
	1P1M	2P1M	2P2M	3P3M	3P2M
Category	Qualified internally	Under-development	MP	MP	MP
Structure	w/o RDL	w/o UBM	ST™ 1L	ST™ 2L	w/o RDL
Features	<ul style="list-style-type: none"> The simplest structure Fastest cycle time Suitable for small die 	<ul style="list-style-type: none"> Relatively low cost and Faster cycle time than 2P2M 	<ul style="list-style-type: none"> Most widely used one 	<ul style="list-style-type: none"> For High I/O density I/O routing flexibility 	<ul style="list-style-type: none"> Magnetic (NiFe) part embedded in WLP
Sub-structure		1P2M	HC™ 1L	As Is / To Be	4P3M
Notes		RDL first		<ul style="list-style-type: none"> 30um UBM UBM Full wetting For better BLR performance for large die by strengthening ball joint. 	w/ RDL
Performance		<ul style="list-style-type: none"> No PI under RDL (CMP required @ fab) 	<ul style="list-style-type: none"> Higher current carrying capacity (2.5A per ball) Lower Rdson 		

RDL | Redistribution Layer



RDL enables the redistribution of the bonding pad from the center of the chip to the edge, facilitating layering of the chip in desired positions without altering the chip's structural design.

Type



Au RDL

This technology enables the implementation SIP by rearranging pad locations. It simplifies and streamlines the process of stack die wire bonding, without requiring changes of the pad layout design of the memory device.

Application :
Mostly used for Multi stack Wire bonding PKG for Memory such as NAND Flash and DRAM
Available for all applications that need Au wire bonding



Direct RDL (Power Device)

In the thick Cu process, a layer is formed directly on the fab passivation without additional lower polymer protective layers. Due to the low resistance of copper, this process provides a higher current efficiency compared to the general aluminum wiring, and the use of various wires such as Au, pure and Pd/Cu wires allows a BOAC process in a stable manner without the complication of cracks.

* BOAC : a layout technology called "Bond Over Active Circuit"

Application :
Wire bonding PKG for Power Management IC and Memory

BUMPING

During the semiconductor packaging and assembly process, electrical connections between semiconductor chips (die) and substrate terminals are secured through a wiring process that involves the formation of bump-shaped metals, rather than the conventional wire bonding technology.

Type



Au Bump

This technology has been developed to replace the wire bonding. With this new technology, the chips with golden bumps go through thermal compressions to be made into COG (Chip on Glass), COF (Chip on Film), or COP (Chip on Plastic) packages.

Application :

TV / Monitor / Notebook / Mobile / Tablet / Automotive

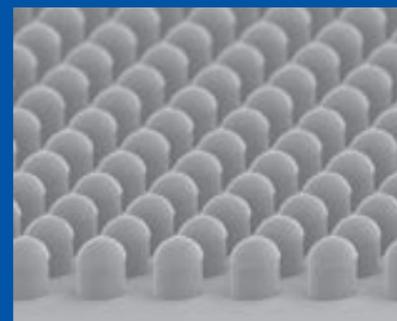


Solder Bump

A solder bump is a small solder ball attached to the pad or contact areas of a semiconductor device, minimizing the length of electric connections between a chip and a substrate.

Application :

fcBGA PKG / SoC / PMIC / Graphics



Cu Pillar Bump

A next-generation bump technology for higher density, reliability, and performance. This satisfies the current and possible future RoHS conditions, and it is used in the connection of flip chips utilizing the benefits of various designs.

Application :

fcBGA and fcQFN PKG / BB & AP Processor / Power Amplifiers / NAND Flash / WiFi Module

CP-TEST | Chip Probe Test

The Electrical Die Sorting (EDS) process is designed to verify the quality characteristics of individual semiconductor chips in the wafer state, allowing defective chips to be screened out and problems to be corrected during the design stage. This results in improved work efficiency in subsequent processes by pre-screening defective chips.

Type



Application	Vendor	Model
DDI	Advantest	T6372(ND2)
		T6373(ND3)
		T6391(ND4C)
		T6391S(ND4ST)
	Yokogawa	TS670
		ST6730A
PMIC	Eagle	ETS-364B
		T2000-IPS
	Advantest	T2000-IPS/EPP
		T2000-IPS 52TH
CIS	Advantest	T2000-ISS/32
		T2000-ISS/64P
SOC	Teradyne	Ultra-FLEX

TOWARDS TOMORROW'S EXCITING TECHNOLOGY

IN THE EVER-CHANGING INDUSTRY, LB SEMICON THRIVES THROUGH CONTINUOUS R&D, MEETING DIVERSE PARTNERS' NEEDS AND EXCEEDING CUSTOMER EXPECTATIONS WITH PRECISE TECHNOLOGIES.

3. Technology

Our Business

FOWLP

High Current WLP

Micro Bump

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LB SEMICON TOTAL SOLUTION

**LB SEMICON DEVELOPS
NEW TECHNOLOGIES
FOR A NEW WORLD
WITH TOP LEVEL TALENTS.**

To create a better future through technology,
we invest heavily in recruiting experts
and conducting extensive research.
As a global OSAT leader, we are committed to
ongoing innovation without complacency.



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FOWLP

FOWLP is composed of epoxy mold compound (EMC). This technology eliminates the need for printed circuit boards (PCBs) in our packages by directly forming the redistribution layer (RDL) and solder balls on top of the EMC.



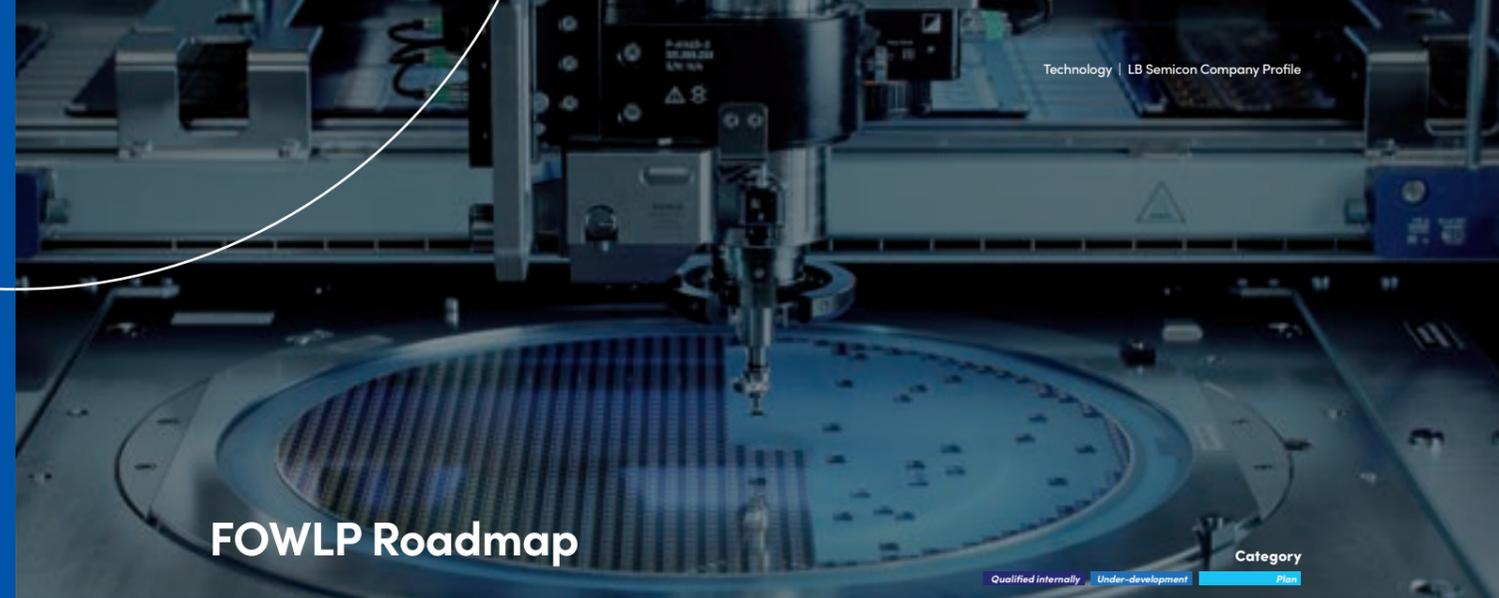
Development

INTERNALLY QUALIFIED 6mm X 6mm SIZE FOWLP

TARGET PRODUCT PMIC, RFIC

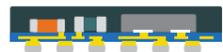
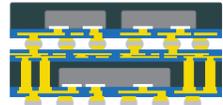
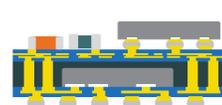
Package information

Layer	Specification
PKG Size	2.6 × 2.6mm ~ 6.0 × 6.0mm (Under-develop 10 × 10mm)
Chip Size	1.73 × 0.97mm ~ 5.0 × 5.0mm (Under-develop 7 × 7mm)
Ball Pitch	≥0.35mm
Mold Thickness	0.30 ~ 0.55mm
Bump Structure	4Layer / 6Layer



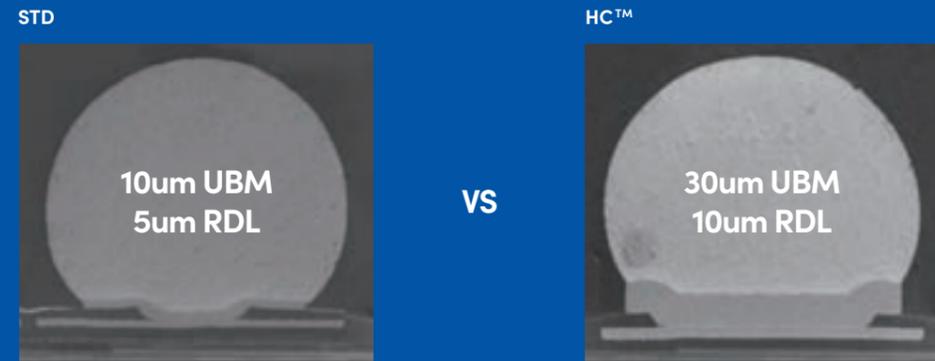
FOWLP Roadmap

Category
Qualified internally Under-development Plan

	Fan-out 	
2020	Feasibility Study Since 2019	
2021 - 2022	FO(S)  Single die	
2023 - 2024	FO(P) FO(M)   Multi-die (Eside by side) Integration with Passive	
2025 -	Integration & High Performance  SiP  Higher level integration by stack-up using TMV	

HIGH CURRENT WLP

The improved structure of WLP in this technology allows us to triple the current compared to conventional methods, Resulting in lower Rdson properties and improved EM properties.



Features

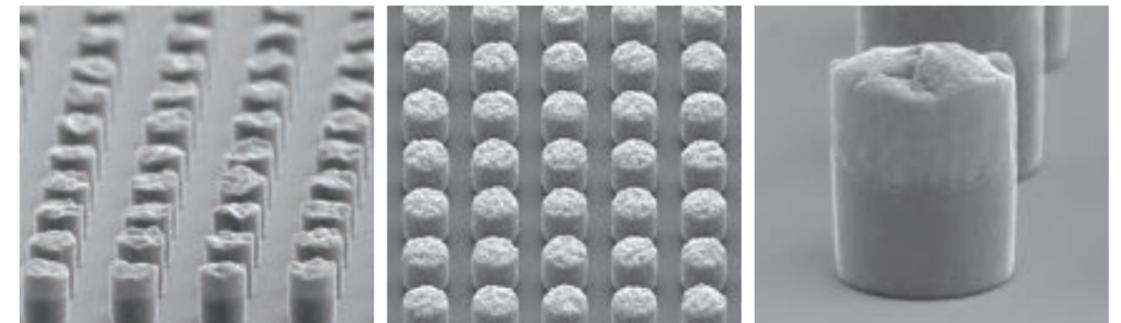
- ELECTRICAL PERFORMANCE**
Low Rdson by thick RDL
Typical WLP : ≤ 6um
HCTM WLP : 10um
- COST EFFECTIVE SOLUTION**
No Use of Expensive Molding Process
Same material and stack-up as traditional 2P2M WLP
- BLR RELIABILITY**
x1.9 Higher BLR TC Performance than typical WLP by full UBM wetting technology
- HIGHER CURRENT CAPACITY**
x3 Higher Current Carrying Capacity by combination of thick UBM & DL

High Current WLP Roadmap

	Category	
	Qualified internally	Plan
Silicon die High Current Carrying Capacity		
2020	HC™ 1L Max. 2.5A	ST™ 2L Max. 1.0A
2021 - 2022	SHC™ Max. 3.5A	HC™ 2L Max. 2.5A
2023 - 2024	SCH™ 2L Max. 3.5A	UCH™ Max. 5.0A
2025 -	High Current Carrying Capacity, Low Rdson	

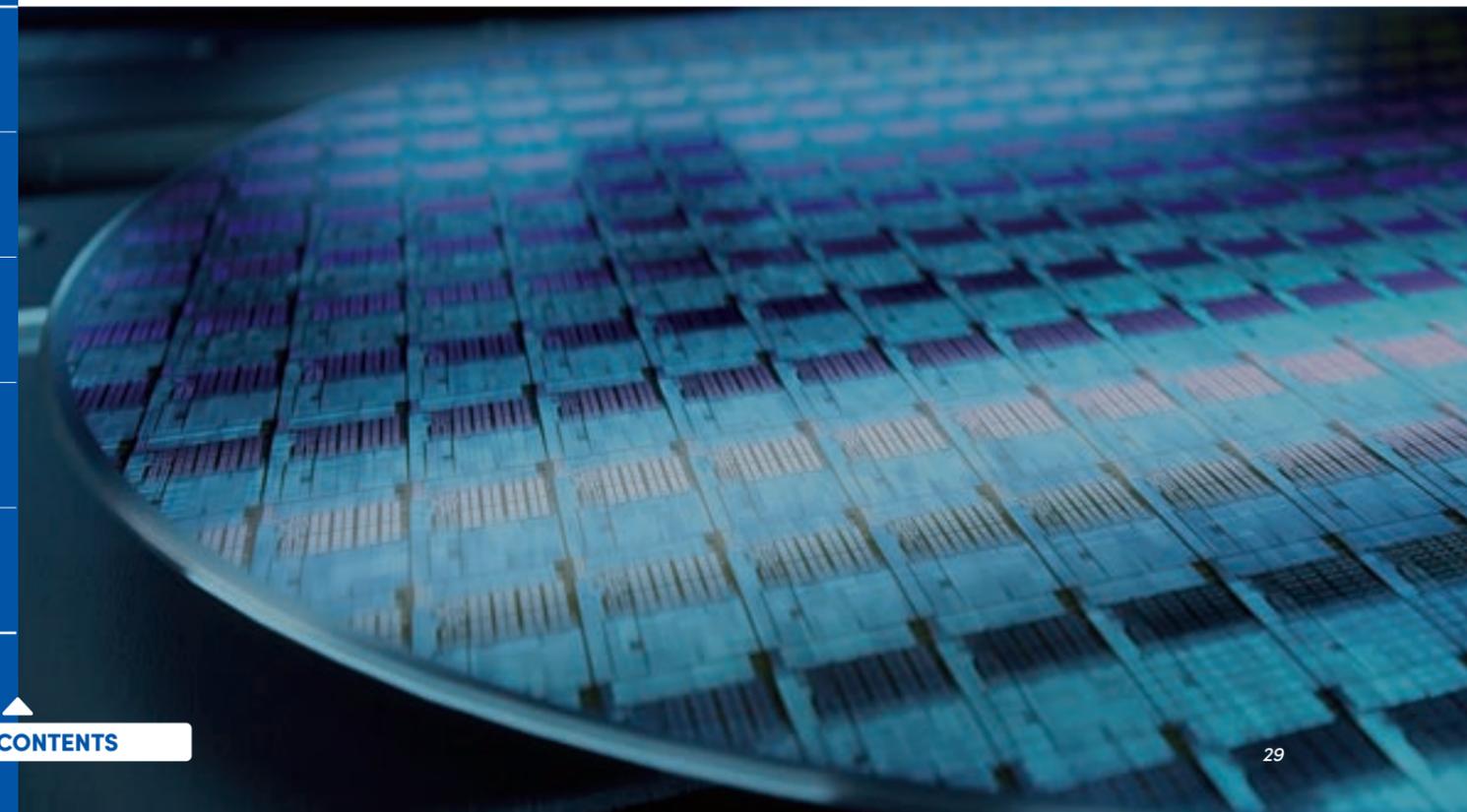
MICRO BUMP

A Micro Bump is a micro pitch bump, no more than 10um. In accordance with the latest technology trend where the I/O Count is increasing, this technology is widely applied to 3D packaging in large numbers. The standard structures include Cu/SnAg, Cu/Ni/SnAg, and Ni/SnAg.



MICRO BUMP Roadmap

	Category					
	Qualified internally	Plan	Plan	Plan	Plan	Plan
Micro-bump	2020	2021	2022	2023	2024	2025
Pitch [um]	15	10	8	6		
Total height [um]		6		4		
Stack-up	Cu/LF cap		Ni/LF cap			



TOWARDS A BETTER SUSTAINABLE FUTURE

THE PURPOSE OF ALL TECHNOLOGY IS TO BENEFIT PEOPLE, SOCIETY, AND THE ENVIRONMENT. LB SEMICON STRIVES TO CREATE THE FUTURE AT ALL TIME.

4. Sustainability

ESG

Environmental Responsibility

Social Responsibility

Quality Responsibility

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ESG

LB SEMICON EMBARKS ON A NEW JOURNEY TOWARDS A SUSTAINABLE FUTURE.

Based on our ideas on business management while respecting the environment and human rights, we strive to become a responsible enterprise that protects future values with improved sustainability and practices, for a better future and a more harmonious society.

Our conviction for a sustainable future will be an important landmark for our journey to a better tomorrow.

FOR THE BETTER WORLD

Our Promise for Sustainability

Environment

We are committed to practicing climate change mitigation and resource circulation through eco-friendly management, minimizing our environmental impact.

Social

We adhere to corporate ethics and take the lead in guaranteeing human rights and establishing cooperative relationships with local communities.

Governance

We aim to build a sound governance structure based on transparency and independence, and to grow together with all stakeholders.

Environment Management System Certificates

ISO 14001 : 2015 / KS I ISO 14001 : 2015
Issued on : 2022-09-23 / Expires on : 2025-09-24

Safety and Health Management Systems Certificates

ISO 45001 : 2018 / KS Q ISO 45001 : 2018
Issued on : 2022-09-23 / Expires on : 2025-12-19

LG Display Carbon Partnership Certificate

Issued on : 2022-09-23 / Expires on : 2025-09-22

LB SEMICON'S EFFORT

ENVIRONMENTAL RESPONSIBILITY

LB SEMICON AIMS FOR SUSTAINABLE COEXISTENCE BETWEEN MANKIND AND EARTH.

LB Semicon is dedicated to opening the door to a carbon-neutral era as well as innovations for the environment, so that everyone can enjoy the beautiful natural environment and sustainable Earth.



Non-CN Type Products



RoHS Packaging



Pb-Free Solder Bump



Lead Free Packaging

GREENHOUSE GAS MANAGEMENT SYSTEM.

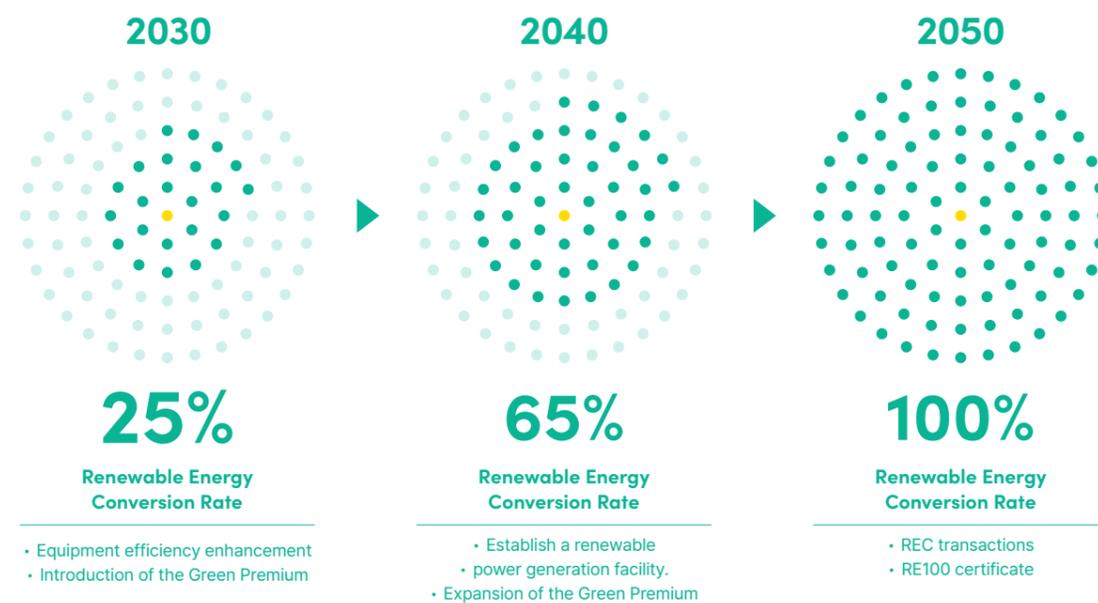
We prioritize addressing climate change in our business operations by setting annual greenhouse gas emission reduction goals, implementing programs to reduce emissions, and verifying emission data through third-party monitoring. To reduce the amount of greenhouse gases emission, we are engaged in a variety of activities to reduce the amount of energy used. We introduced high-efficiency equipment and applied inverters to reduce the amount of electricity we use and collect waste heat to replace fossil energy.



CONVERTING TO RENEWABLE ENERGIES.

We have a roadmap to convert our energy sources to renewables for our businesses. To improve equipment efficiency, we'll install power generation equipment like solar panels while minimizing energy consumption. Through green premiums and REC transactions, we aim to achieve 100% renewable energy conversion by 2050.

LOOK BEYOND THE PRESENT



[Mid/Long-term Road map for Renewable Energies]

Waste Treatment Process

We handle the waste materials from our business in accordance with applicable laws and regulations through a qualified third-party contractor. Moreover, using the Allbaro system of Korea Environment Corporation, we link all phases of wastes from generation to treatment to our system to manage them.

We believe that it is our responsibility to reduce our carbon footprint and protect the planet for future generations, which is why we prioritize waste recycling and resource conservation.

Recycling Wastes

We reduce the amount of wastes originating from semiconductor processes and minimize the amount of chemicals used to reduce the amount of emission of designated wastes. In addition, to build a resource recycling system, we hired a contractor to recycle the waste materials that used to be incinerated, neutralized, or dumped in a landfill to enhance the recycling rate of wastes.

Through these recycling processes, we are able to repurpose materials that would otherwise go to waste, and reduce our overall environmental impact.

Recycling Water Resources

In order to enhance efficiency in using water resources, we have been reusing water as U/T water. We have also been running a wastewater treatment facility in-house, so that the waste water is transferred to the wastewater treatment plant to treat it safely.

Our dedication to recycling water resources is just one example of our company's commitment to sustainable and responsible business practices, and we are constantly seeking new ways to reduce our environmental impact.

SOCIAL RESPONSIBILITY

LB SEMICON CONTRIBUTES TO BUILDING A BRIGHTER FUTURE IN SOCIETY.

A company cannot grow by itself. It requires the support and trust of the members of society. To coexist with society, we actively engage in social responsibility programs, earn the trust of interested parties, and eventually work to build a better tomorrow with the community.

BUILDING A SAFE WORKPLACE FOR OUR EMPLOYEES AND PARTNERS.

We prioritize a safe working environment by introducing ten safety rules for workers. Responding promptly to dangerous situations through the Danger Report Center, and implementing a suggestion system and Safety e-Report for continuous safety improvement.

ADVANCING SAFETY AND HEALTH MANAGEMENT SYSTEM THROUGH ONGOING EFFORTS.

We operate with a Safety and Health Management System following our ISO 45001 certification, regularly updating our safety standards to align with social trends. We also implement a permit system for outsourced construction work and a qualification system for chemical handlers to prioritize safety in our operations.



LOOK BEYOND THE BOUNDARY

01. JOB CREATION

- Creation of jobs for the youth, middle-aged populations, and people with disability.

02. PROVIDING SUPPORT TO THE CARE OF CHILDREN AND ADOLESCENTS

- Regular support provided to children from the second-lowest income population group in the local community.
- Providing support and engaging in volunteer activities for the Child Welfare Center in the local community.
- Sponsoring juvenile crime prevention activities within the community.

03. ENVIRONMENT IMPROVEMENT ACTIVITIES FOR THE LOCAL COMMUNITY

- Environment improvement activities within the industrial complex.

04. CULTURE AND ART SPONSORSHIP

- Sponsoring promising young artists.

05. PROVIDING SUPPORT TO THE ELDERLY AND WOMEN

- Providing sponsorship to the long-term care homes in the area.
- Providing support to the Women's Independent Support Group for Former Sex Workers in the area.

COMPLIANCE WITH THE PROHIBITION ON THE USE OF CONFLICT MINERALS.

We are participating in the prohibition scheme against conflict minerals.

LB Semicon is fully aware of the seriousness of issues such as exploitation of labor, sexual violence, and other human rights violations as well as damages to the environment and pollution in the mining processes of minerals from areas in conflicts or dangerous areas. In order to minimize such negative impacts, we actively comply with the regulations against the use of conflict minerals by SEC and follow the international guidelines as we continue to give our efforts and attention to the matter.



QUALITY RESPONSIBILITY

LB SEMICON PROVIDES THE BEST SERVICES & PRODUCTS THROUGH QUALITY CONTROL.

LB Semicon prioritizes customer satisfaction through its comprehensive total solution services, ensuring the highest quality and best service, accessible anytime and anywhere.

Our Promise to Quality

Quality Management Certificates

Quality Management System Certificate:
IATF 16949 : 2016

HSPM certificate:
IECQ QC 080000 : 2017(HSPM)

Quality Management System Certificate:
ISO 9001 : 2015 / KS Q ISO 9001 : 2015

Samsung Electronics Eco-Partner Affiliate Company

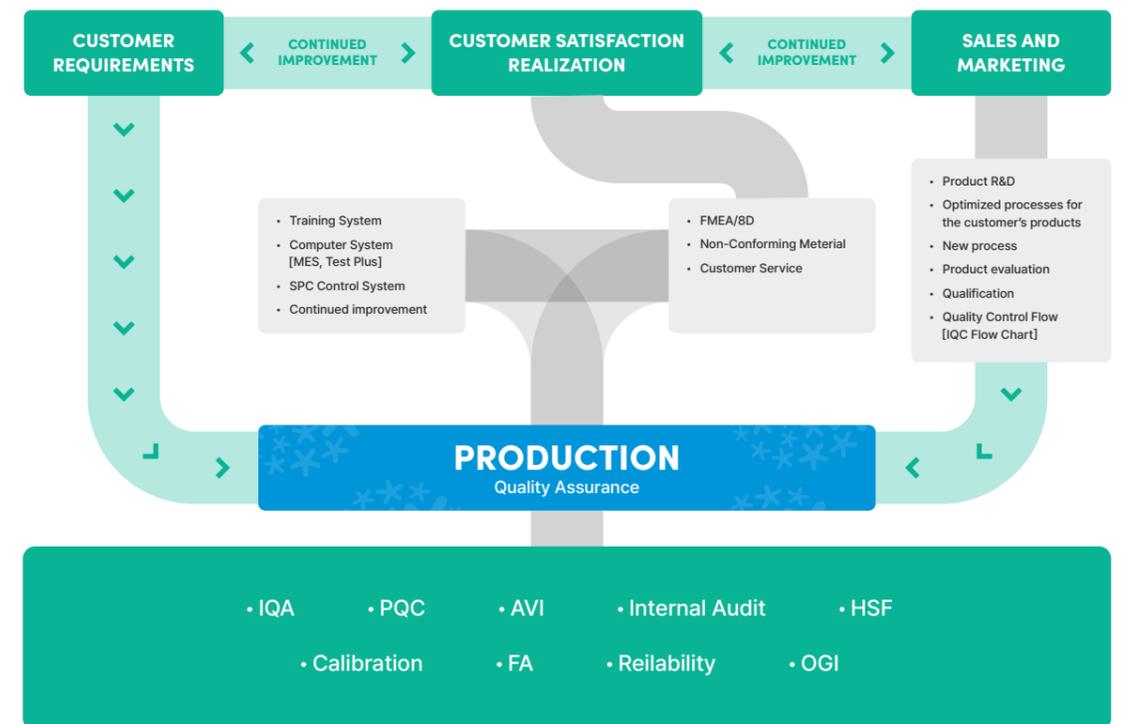
ANSI/ESD S20.20 certificate:
ANSI/ESD S20.20

Sony Green Partner

WE HAVE INTRODUCED A WELL-ORGANIZED PROCESS TO ENSURE CUSTOMER SATISFACTION.

To ensure customer satisfaction, we have implemented a streamlined process that encompasses coordination with customer requirements, sales and marketing, and training systems. We utilize computer systems like MES and Test Plus, along with FMEA/BD, customer service, and product R&D. Our optimized processes include product evaluation, qualification, and quality control. The IQC flow chart outlines the entire process, ensuring adherence to the highest standards of quality assurance.

LOOK BEYOND THE SATISFACTION



01. Customer Satisfaction

We attentively listen to the voice of our customers, actively discerning their needs. Collaboration is our mission as your OSAT partner.

No matter what concerns you may have, we stand ready to be your partner, sharing in the discussion of your challenges together.

02. Reliable Quality

In the semiconductor industry where precision is paramount, it is essential to provide services of reliable quality.

We establish advanced goals and strive to deliver optimal services tailored to our customers' perspectives, rather than solely focusing on our own vantage point.

03. Continued Improvement

In our relentless pursuit to transform our customers' aspirations for a better future into tangible reality.

We refuse to settle in the present and instead strive continuously for technological advancement. As long as your dreams persist, our efforts will never cease, ensuring an unwavering commitment to your success.

NETWORK

BE THE HERO OF THE INNOVATION FOR TOMORROW WITH LB SEMICON.



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